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Part Number: [0432498919](#)
Status: **Active**
Overview: [modular_plugs_jacks](#)
Description: Modular Jack, Right Angle, Low Profile, 8/8, Panel Stops

Documents:

3D Model	Product Specification PSX-43249 (PDF)
Drawing (PDF)	RoHS Certificate of Compliance (PDF)

Agency Certification

CSA	LR19980
UL	E107635

General

Product Family	Modular Jacks/Plugs
Series	43249
Component Type	PCB Jack
Magnetic	No
Overview	modular_plugs_jacks
Performance Category	3, 4
Power over Ethernet (PoE)	N/A
Product Name	RJ45

Physical

Boot Color	N/A
Color - Resin	Black
Durability (mating cycles max)	500
Flammability	94V-0
Inverted / Top Latch	No
Lightpipes/LEDs	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Orientation	Right Angle (Side Entry)
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness Recommended (in)	0.062 In
PCB Thickness Recommended (mm)	1.57 mm
Packaging Type	Tray
Panel Mount	Without Flange
Pitch - Mating Interface (in)	0.040 In
Pitch - Mating Interface (mm)	1.02 mm
Pitch - Term. Interface (in)	0.050 In
Pitch - Term. Interface (mm)	1.27 mm
Plating min: Mating (µin)	50
Plating min: Mating (µm)	1.25
Plating min: Termination (µin)	100
Plating min: Termination (µm)	2.5
Ports	1
Positions / Loaded Contacts	8/8
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-40°C to +85°C
Termination Interface: Style	Through Hole
Waterproof / Dustproof	No
Wire/Cable Type	N/A

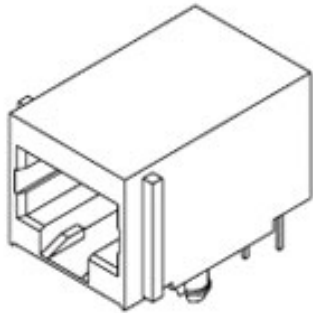


image - Reference only

Series

EU RoHS

**ELV and RoHS
Compliant**
REACH SVHC
Not Reviewed
**Halogen-Free
Status**

Not Reviewed

**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

China RoHS



Search Parts in this Series
[43249Series](#)

Mates With
FCC 68 Plugs

Electrical

Current - Maximum per Contact	1.5A
Grounding to PCB	Yes
Grounding to Panel	Yes
Shielded	Yes
Voltage - Maximum	150V AC (RMS)

Solder Process Data

Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-44050-004
Product Specification	PSX-43249
Sales Drawing	SDA-43249

This document was generated on 06/07/2010

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NOTES:

1) MATERIAL:

HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
INSULATOR: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE, .012/(0.30) THICK
SHIELD: BRASS, .007/(0.18) THICK

2) FINISH:

TERMINALS:

- A = SELECT GOLD IN CONTACT AREA: 50 MICROINCHES / 1.27 MICROMETERS MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.
B = SELECT GOLD IN CONTACT AREA: 30 MICROINCHES / 0.76 MICROMETERS MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.

SHIELD:

- *100 MICROINCHES / 2.54 MICROMETERS NICKEL OVER 50 MICROINCHES /
1.27 MICROMETERS COPPER UNDERPLATE, PCB GROUND TABS DIPPED IN TIN
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS
DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD
IN THE PC TAILS AND/OR SHIELD.

3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43249.

4) PACKAGING SPECIFICATION:

- UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS
PER MOLEX PACKAGING SPECIFICATION PK-43249-004.
UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN TUBES
PER MOLEX PACKAGING SPECIFICATION PK-43249-005.
SHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS
PER MOLEX PACKAGING SPECIFICATION PK-44050-004.

5) MATES WITH: MODULAR PLUGS THAT CONFORM TO FCC REGULATION PART 68.5.

6) SEE SHEET 3 FOR SHIELDED JACK ASSEMBLY.

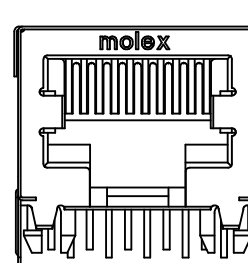
7) SEE SHEETS 5 & 6 FOR P.C. BOARD LAYOUTS.

8) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.

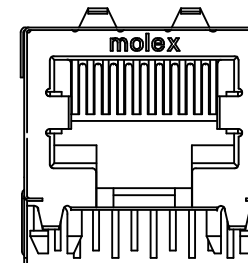
9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

10) THIS PART CONFORMS TO FCC REGULATION 68.5 AND TIA 1096 FOR MODULAR JACKS.

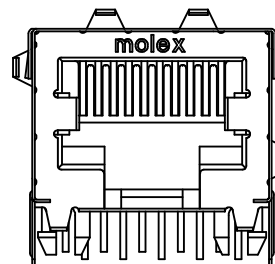
SIDE/TOP GROUND TAB OPTIONS FOR SHIELDS



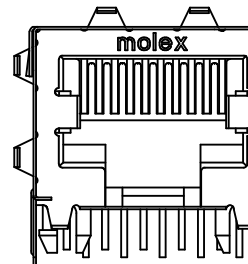
OPTION "A"
NO TOP OR SIDE TABS



OPTION "B"
TOP TABS

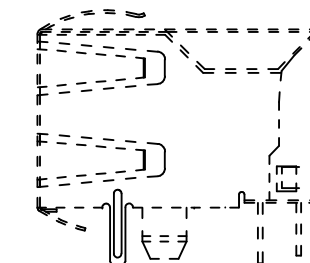


OPTION "C"
TOP AND STAGGERED SIDE TABS

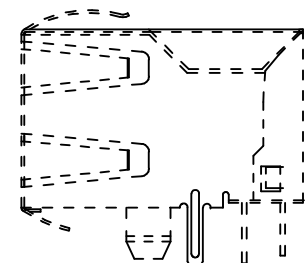


OPTION "D"
TOP AND SIDE TABS

BOTTOM PCB GROUND TAB OPTIONS FOR SHIELDS



OPTION "E"
OPTIONAL FRONT POSITION



OPTION "F"
OPTIONAL REAR POSITION

NOTE: EITHER PCB GROUND TAB OPTION IS AVAILABLE
ON ALL SIDE/TOP TAB CONFIGURATIONS

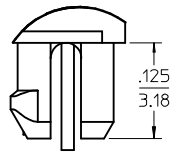
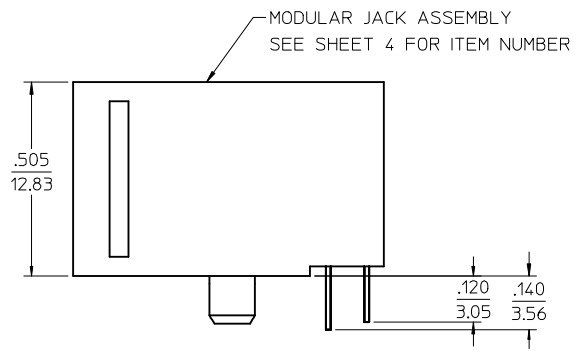
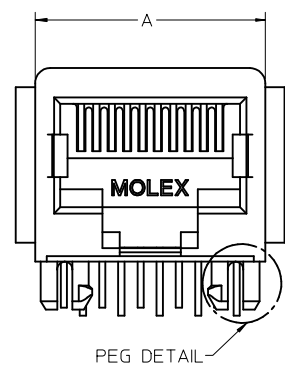
DRAWING LEGEND

- SHEET 1- NOTES, GROUND TAB OPTIONS
SHEET 2- UNSHIELDED MODULAR JACK
SHEET 3- SHIELDED MODULAR JACK WITH
OPTIONAL SIDE/TOP GROUND TABS & BOTTOM GROUND
TAB WITH OPTIONAL POSITION.
SHEET 4- PART NUMBER CHARTS
SHEET 5- FOOTPRINT LAYOUT FOR 8 POSITION HOUSING
SHEET 6- FOOTPRINT LAYOUT FOR 6 POSITION HOUSING

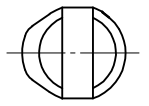
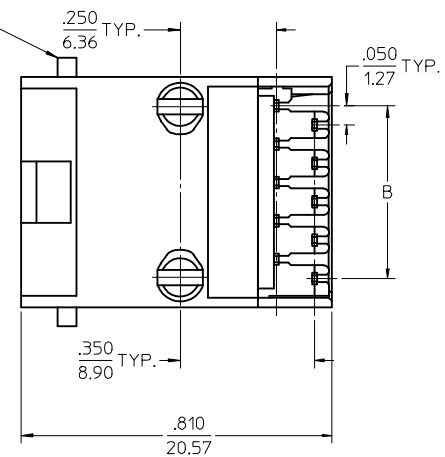
ADDED NOTE 10 EC NO: UCP2009-0740 DRWN: KLOSTERNER 2008/09/29 CHKD: JEBELL 2008/10/03 APPR: FSMITH 2008/10/03	DESCRIPTION ▽=0 ▽=0	QUALITY SYMBOLS		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE		DESIGN UNITS		THIRD ANGLE PROJECTION	
						IN/MM		4:1		INCH			
						DRAWN BY DATE		TITLE					
						JTR 1993/06/23		LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY					
						CHECKED BY DATE							
						JTR 1993/06/23							
K1 REV						APPROVED BY DATE		MOLEX MOLEX INCORPORATED					
						RAS 1993/06/23							
				ANGULAR ±1/2°		MATERIAL NO.		DOCUMENT NO.				SHEET NO.	
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 4		SDA-43249				1 OF 6	
						SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

UNSHIELDED MODULAR JACK

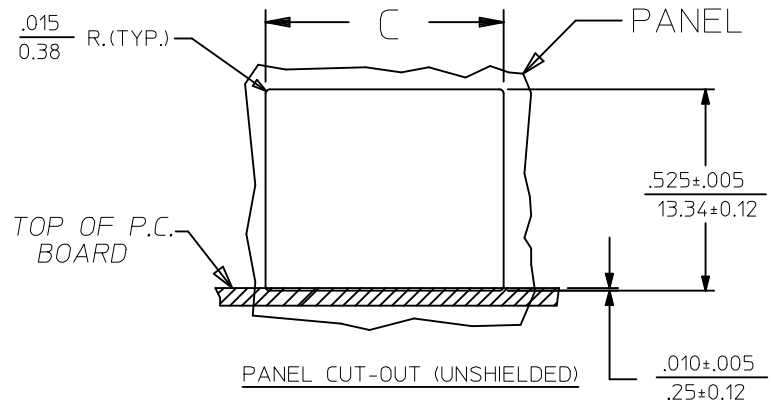
8 POSITION LOADED 10 SIZE SHOWN



OPTIONAL FLANGE
USED FOR FLUSH
MODULAR JACK



PEG DETAIL
SCALE 8:1

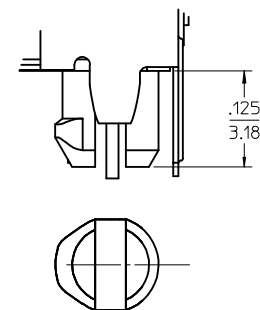
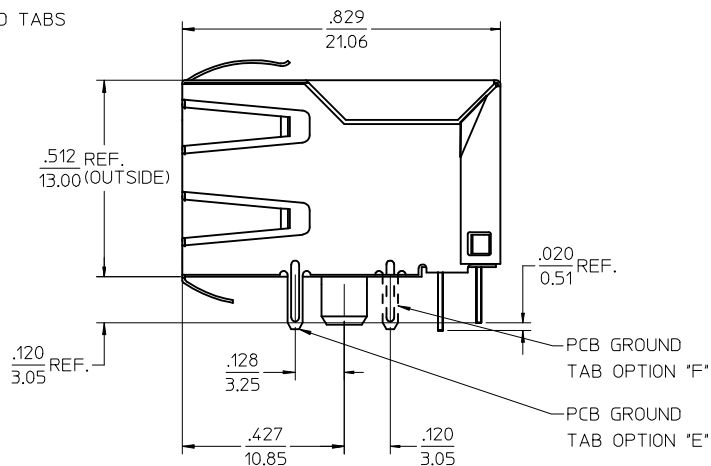
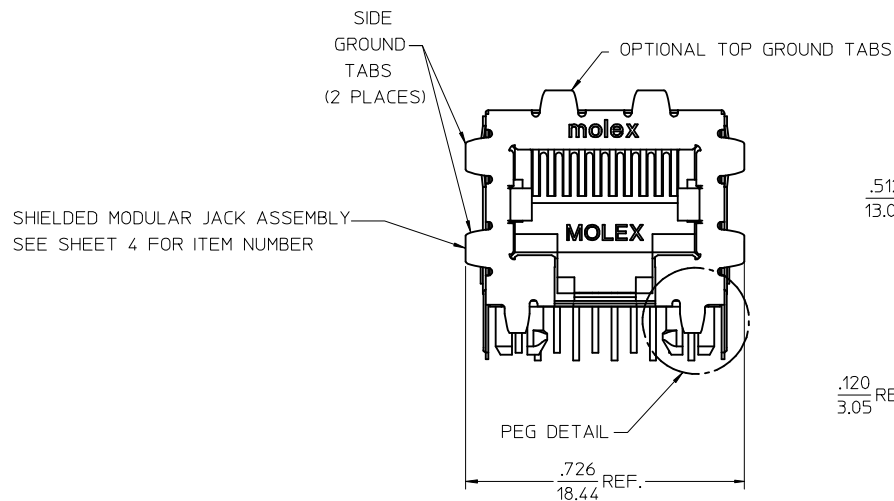


HOUSING SIZE	CIRCUIT SIZE	DIM. A	DIM. B	DIM. C
8	10	.600±.005 (15.24±0.13)	.450±.005 (11.43±0.13)	.620±.005 (15.75±0.13)
8	8	.600±.005 (15.24±0.13)	.350±.005 (8.89±0.13)	.620±.005 (15.75±0.13)
8	4	.600±.005 (15.24±0.13)	.150±.005 (3.81±0.13)	.620±.005 (15.75±0.13)
8	6	.600±.005 (15.24±0.13)	.250±.005 (6.35±0.13)	.620±.005 (15.75±0.13)
6	6	.520±.005 (13.21±0.13)	.250±.005 (6.35±0.13)	.540±.005 (13.72±0.13)
6	4	.520±.005 (13.21±0.13)	.150±.005 (3.81±0.13)	.540±.005 (13.72±0.13)
6	2	.520±.005 (13.21±0.13)	.050±.005 (1.27±0.13)	.540±.005 (13.72±0.13)

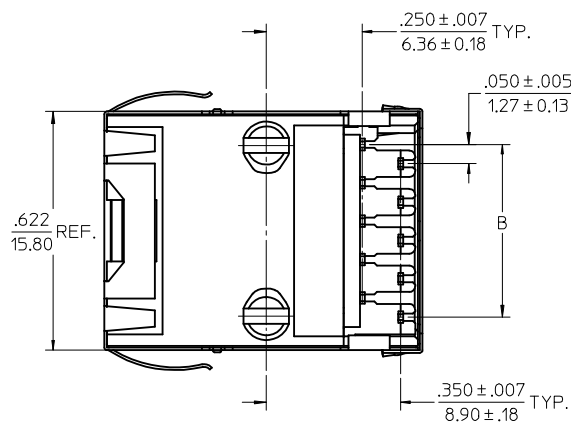
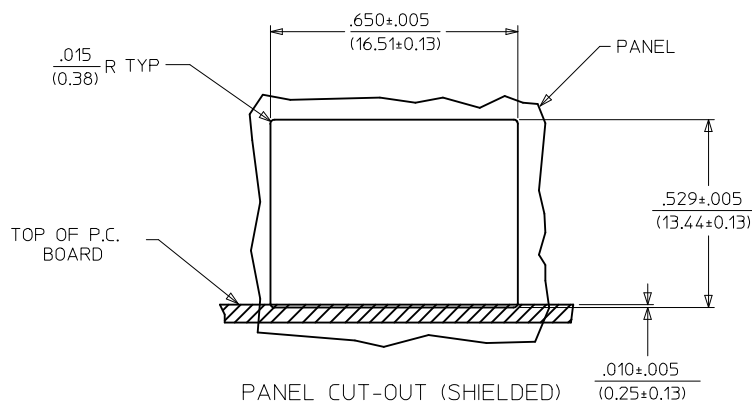
SEE SHEET 1 EC NO: UCP2009-0740 DRWN: JLOSTEME/ER 2008/09/29 CHKD: JBEL 2008/10/03 APPR: FSMITH 2008/10/03	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1/2°	DIMENSION STYLE IN/MM DRAWN BY DATE JTR 1993/06/23 CHECKED BY DATE JTR 1993/06/23 APPROVED BY DATE RAS 1993/06/23	SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	TITLE LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY	MATERIAL NO. RAS	DOCUMENT NO. SDA-43249	SHEET NO. 2 OF 6
K1	REV	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

MODULAR JACK W/ .007" THICK SHIELD AND OPTIONAL GROUND TABS

8 LOADED 10 VERSION SHOWN WITH GROUND TAB OPTIONS "D" AND "E"



PEG DETAIL
SCALE 8:1



DESCRIPTION OF GROUND TAB OPTIONS:
(SEE SHEET 4 FOR AVAILABLE COMBINATIONS OF OPTIONS)

GROUND TAB OPTION	DESCRIPTION
A	NO GROUND TABS
B	TOP TABS ONLY
C	STAGGERED SIDE TABS
D	TOP AND SIDE TABS
E	PCB GROUND TAB IN FRONT POSITION
F	PCB GROUND TAB IN REAR POSITION

HOUSING SIZE	CIRCUIT SIZE	B
8	10	.450 ± .005 11.43 ± 0.13
8	8	.350 ± .005 8.89 ± 0.13

SEE SHEET 1
EC NO: UCP2009-0740
DRWN: JKLOSTEMEIER 2008/09/29
CHKD: JELL 2008/10/03
APPR: FSMITH 2008/10/03

QUALITY SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES ±	± .010	± .004
3 PLACES ±	± .010	± .004
2 PLACES ±	± .025	± .010
1 PLACE ±	± .050	± .020

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
IN/MM

DRAWN BY DATE
JTR 1993/06/23

CHECKED BY DATE
JTR 1993/06/23

APPROVED BY DATE
RAS 1993/06/23

MATERIAL NO.
SEE SHEET 4

SIZE
C

SCALE
4:1

DESIGN UNITS
INCH

THIRD ANGLE PROJECTION

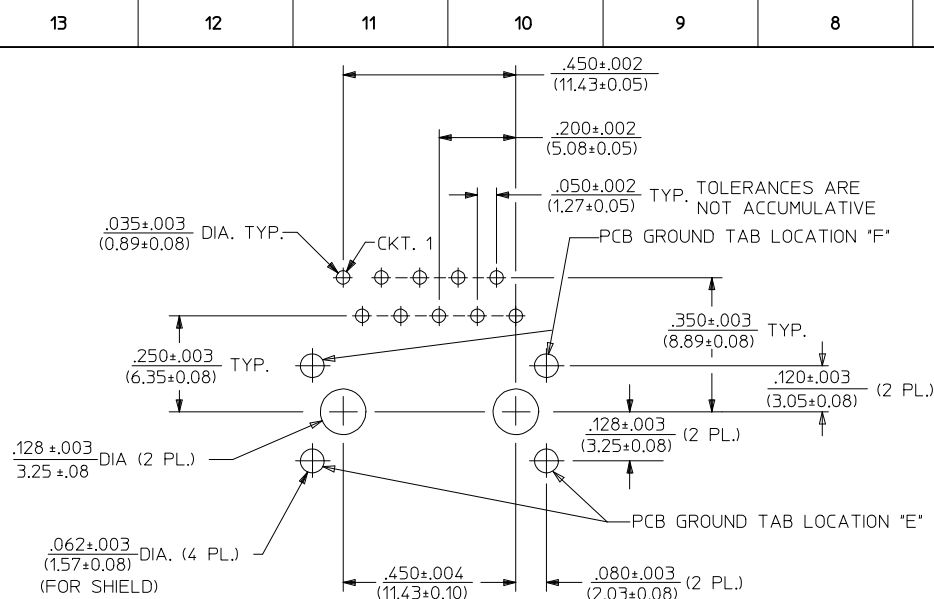
TITLE
LOW PROFILE RIGHT ANGLE
MODULAR JACK ASSEMBLY

MOLEX INCORPORATED

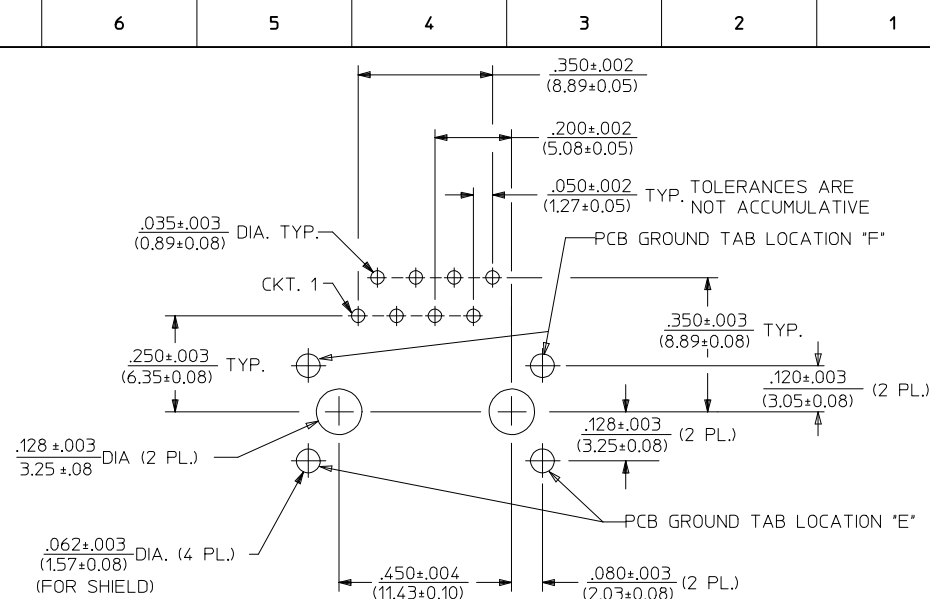
DOCUMENT NO.
SDA-43249

SHEET NO.
3 OF 6

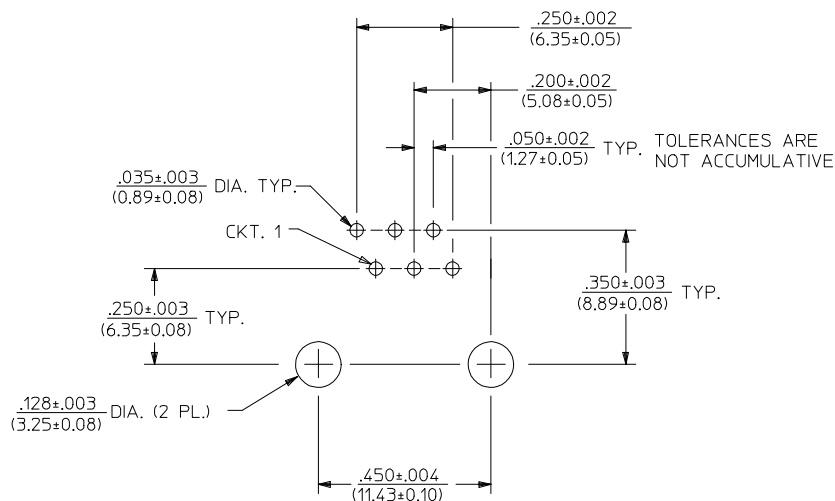
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PC BOARD LAYOUT FOR SIZE 8, 10 CIRCUIT
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 8, 8 CIRCUIT
(COMPONENT SIDE OF BOARD)

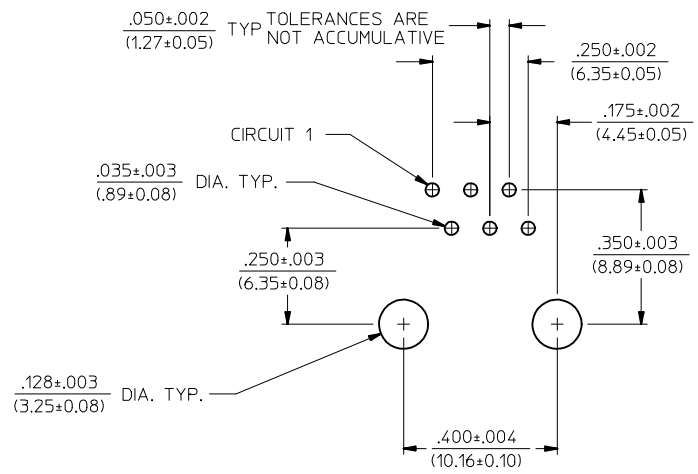


PC BOARD LAYOUT FOR SIZE 8, 6 CIRCUIT
(COMPONENT SIDE OF BOARD)

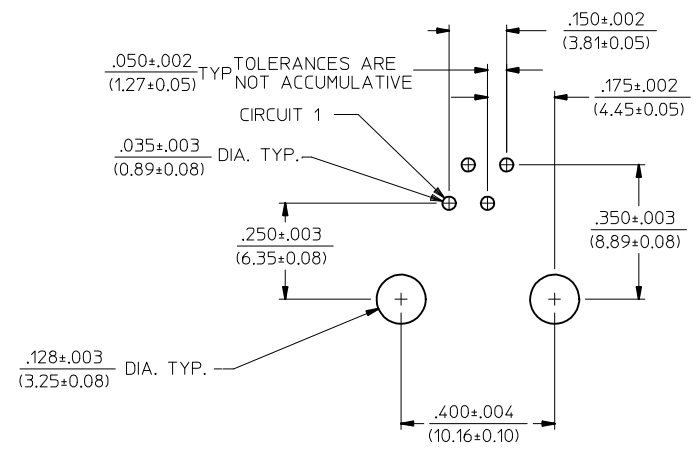
NOTES:
1. RECOMMENDED PCB THICKNESS: .062 ± .005 / (1.57 ± 0.13)

SEE SHEET 1	EC NO: UCP2009-0740 DRWN: JLOSTEMEIER 2008/09/29 CHKD: J.BELL 2008/10/03 APPR: FSMITH 2008/10/03	REV DESCRIPTION K1	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	TITLE LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY		
					mm	INCH	DRAWN BY JTR	DATE 1993/06/23	MOLEX MOLEX INCORPORATED				
				4 PLACES	± ---	± ---	CHECKED BY JTR	DATE 1993/06/23	MATERIAL NO.				
				3 PLACES	± ---	± .010	APPROVED BY	DATE	DOCUMENT NO.				
				2 PLACES	± 0.25	± ---	RAS	1993/06/23	SEE SHEET 4				
				1 PLACE	± ---	± ---	SHEET NO.			5 OF 6			
				ANGULAR ±1/2°			SIZE			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS									

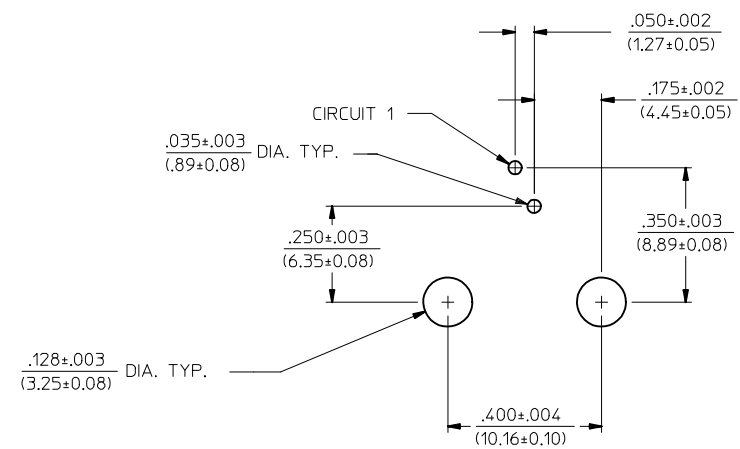
13 12 11 10 9 8 7 6 5 4 3 2 1



PC BOARD LAYOUT FOR SIZE 6, 6 CIRCUIT
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 6, 4 CIRCUIT
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 6, 2 CIRCUIT
(COMPONENT SIDE OF BOARD)

NOTES:
1. RECOMMENDED PCB THICKNESS: .062±.005/(1.57±0.13)

SEE SHEET 1 EC NO: UCP2009-0740 DRWN: KLOSTEWIEC 2008/09/29 CHKD: J.BELL 2008/10/03 APPR: FSMITH 2008/10/03	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	 THIRD ANGLE PROJECTION
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	mm	INCH	DRAWN BY	DATE	TITLE LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY	
				4 PLACES ± ---	± ---	JTR	1993/06/23		
				3 PLACES ± ---	± .010	CHECKED BY	DATE		
				2 PLACES ± 0.25	± ---	JTR	1993/06/23		
				1 PLACE ± ---	± ---	APPROVED BY	DATE		
ANGULAR ±1/2°		RAS	1993/06/23	 MOLEX INCORPORATED					
		MATERIAL NO.	SEE SHEET 4		DOCUMENT NO.	SDA-43249	SHEET NO. 6 OF 6		
K1	REV				SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.